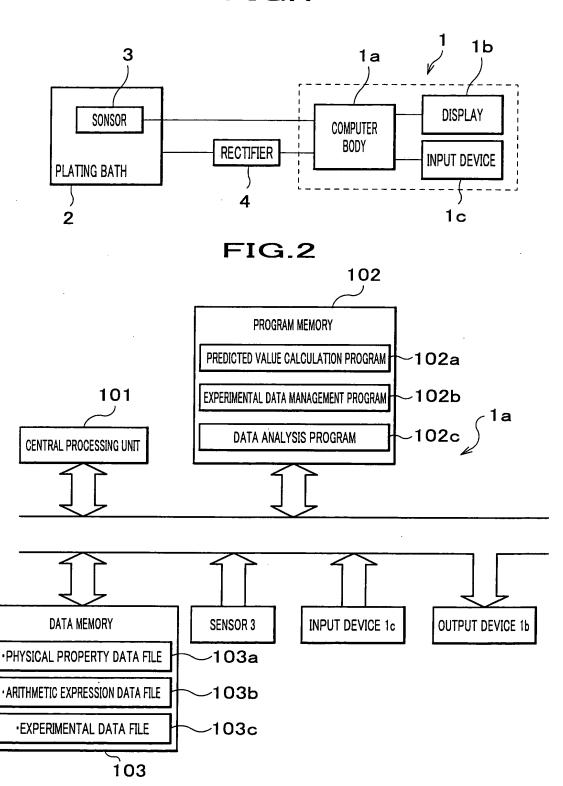
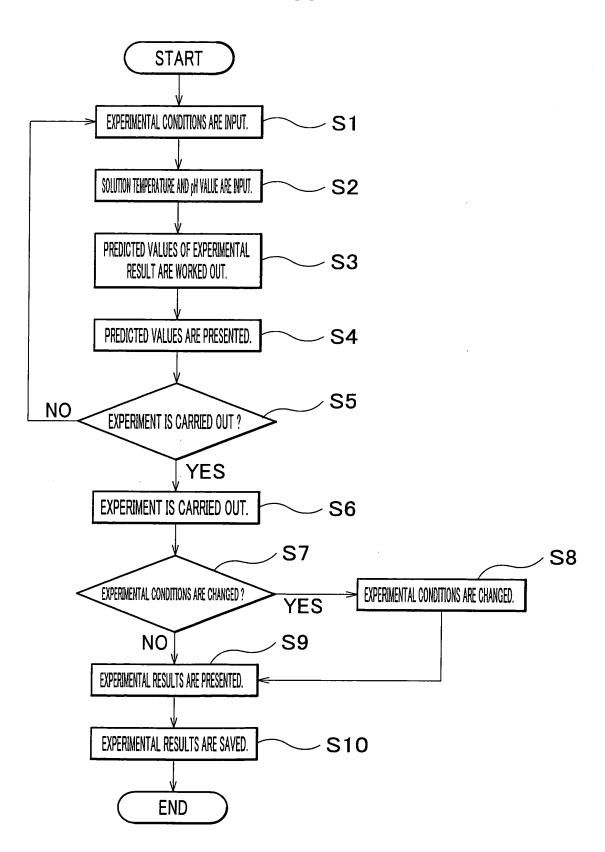


FIG.1

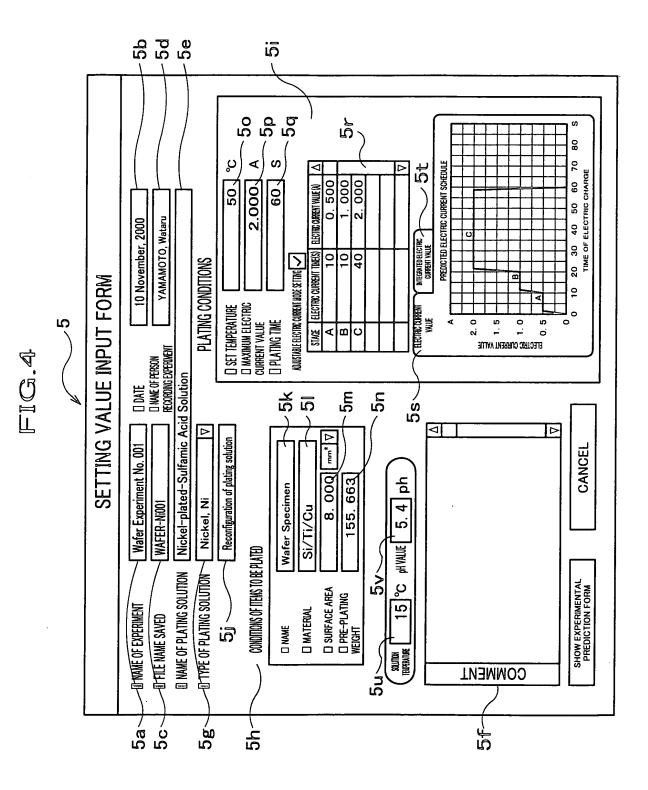


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FIG.3



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## FIG.5A

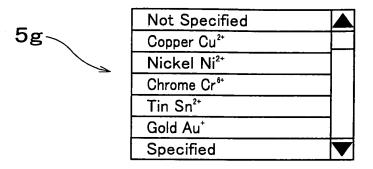


FIG.5B

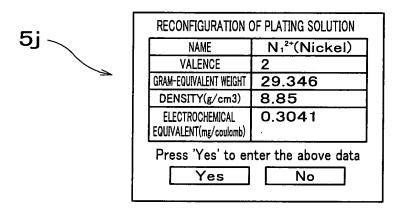
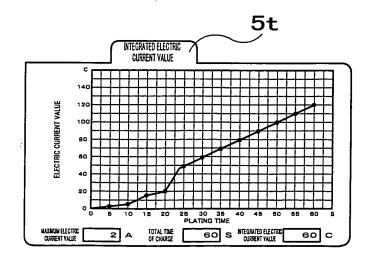
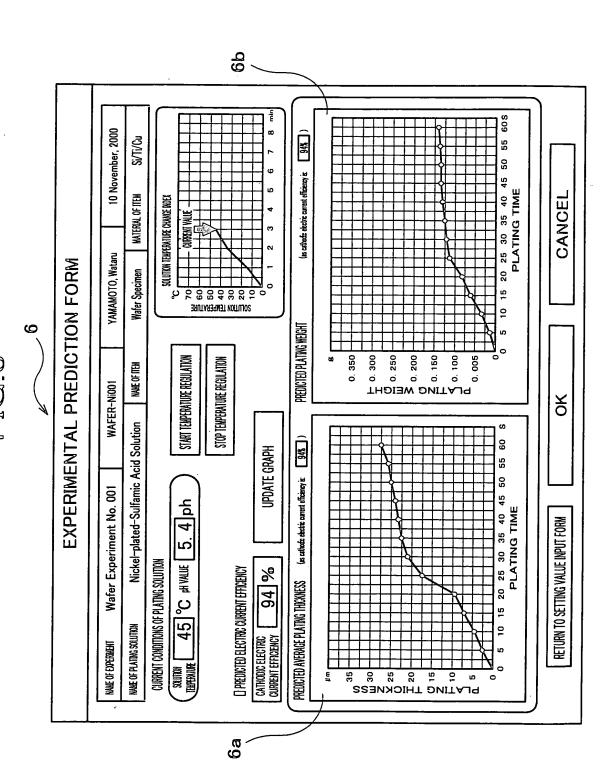


FIG.5C

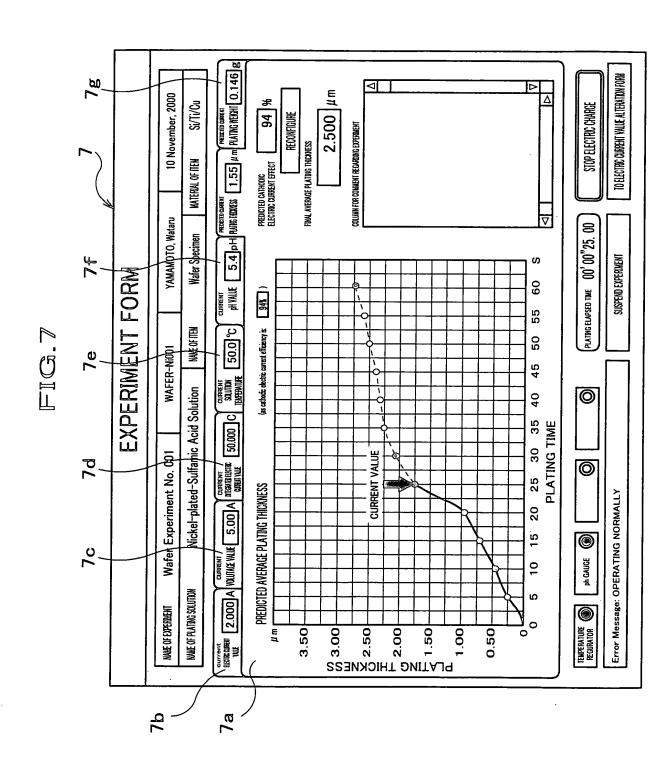


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CHANCE IN PLATING NEIGHT 2.5 µm 5.4 pH 50.000 C 50.0 ເ 10 November, 2000 Sk/Ti/Cu 2.436 2.000 5.00 93.2 0.146 0.135 PRE-PLATING WEIGHT 155.663 POST PLATING WEIGHT 155,798 **8** ELECTRIC CURRENT VALUE CHANCE IN PLATING THICKNESS PLATING THICKNESS INPUT RESULT SOLUTION TEMPERATURE MATERIAL OF ITEM AVERAGE CATHODIC ELECTRIC CURRENT EFFICENCY FINAL AVERAGE PLATING THICKNESS ATERNIA EKSTALOREGIYALE PLATING WEIGHT DEPOSITED PLATING WEIGHT VOLTAGE VALUE TO EXPERIMENTAL RESULT NUMERIC VALUE FORM PH VALUE  $\infty$ AMALYSIS FORM YAMAMOTO, Wataru S 22 PLATING TIME Wafer Specimen CHANGE IN pH VALUE S E 9 84.2 55 15.5 8 NAME OF ITEM 20 CHANCE IN SOLUTION TELEPERATURE 2.24 WAFER-Ni001 45 02.2 Nickel-plated-Sylfamic Acid Solution 2.15 8 ATING TIME SECONDS 35 CHANGE'N MTEGRATED ELECTRIC CURRENT VALUE 70.5 06. f Wafer Experiment Np. 001  $\triangleright$ EXPERI 5 09. r 80 **CHANGE IN PLATING THICKENSS** 20 **96**.0 CHANGE IN VOLUTAGE VALUE 5 07.0 CALIBRATED IN 0 44.0 NAME OF PLATING SOLUTION വ 22.0 CHANGE IN ELECTRIC CURRENT VALUE NAME OF EXPERIMENT 0 00.0 3.00 E 3.50 2.50 2.00 1.00 0.50 1.50 0 **JULAY** PLATING PLATING THICKNESS დ დ



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EXPERIMENTAL RESULT NUMERICAL VALUE FORM

10 November, 2000 Si/Ti/Cu MATERIAL OF ITEM YAMAMOTO, Wataru Wafer Specimen NAME OF ITEM WAFER-Ni001 Nickel-plated-Sulfamic Acid Solution Wafer Experiment No. 001 NAME OF PLATING SOLUTION NAME OF EXPERIMENT

PLATING TIZERS)

PLATING WEIGHTLE MEGRADO ELCITA CONTROLEYA X X X X VALIAE VALIEA X X X X

XXXX XXXX XXXX XXXX ××× XXXX XXXX XXXXXX XXXX XXXX XXXX ××× ××× XXXX ELECTRIC CURRENT VALUE(A) XXXX XXXX XXXX XXXX ××× XXXX ×××× ×××

SAVE IN CSV FORMAT

XXXX

30 28 27 28

XXXX

XXXX XXXX

XXXX XXXX XXXX

XXXX

XXX XXXX XXXX

22 23

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×××